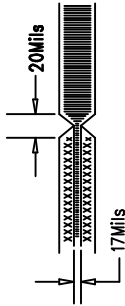


REVISIONS			
REV	DESCRIPTION	APPR	DATE

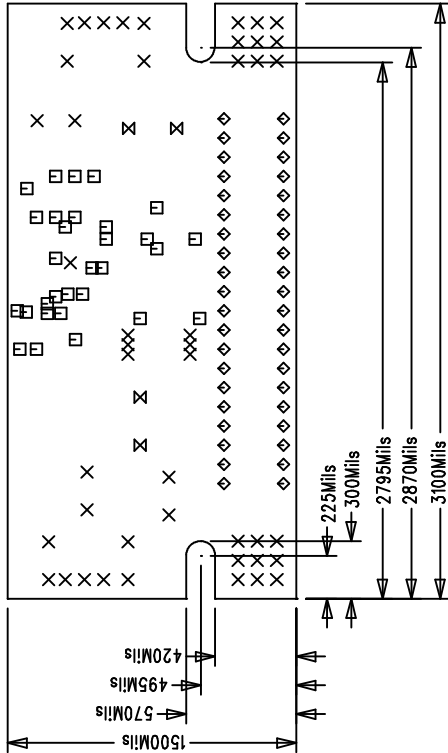
NOTES: Unless Otherwise Specified

1. MATERIAL: 4 Layers, 0.062" THK. FR-4 Glass Epoxy 2 OZ. Copper Clad.
2. All Holes Shall be Plated Thru.
3. Plate Thru Holes With Copper .0014 Min. Thickness. All Hole Sizes In Hole Table Are After Plating.
4. SILKSCREEN: With White Epoxy Non-Conductive Ink.
- 5 PROCESS: Solder Mask Over Bare Copper.
6. SOLDER MASK: LPI, Green.
7. Scoring :

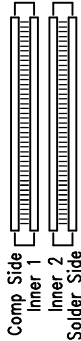


SIZE	QTY	SYM	PLTD
25	45	X	PLTD
15	30	□	PLTD
35	40	◇	PLTD
55	4	⊗	PLTD


LINEAR TECHNOLOGY
LTC1753(Demo Ckt 162B)
Pentium Pro VRM 8.1



Layer Construction



Fabrication Drawing

APPROVALS					1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE				
DRAWN						
CHECK						
DESIGN	Rmb					
ENGR	Cvarg					
			TITLE: Pentium Pro VRM 8.1			
			SIZE	DEMO BRD	REV.	B
			NONE	162		
SCALE = NONE			DES-0167		SHT 1 of 1	